



Material Content Data Sheet



Sales Product Name		TDA21241		Issued		24. January 2018		
MA#		MA001650104						
Package		PG-IQFN-30-2		Weight*		55.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.304	2.34	2.34	23411	23411
leadframe	inorganic material	phosphorus	7723-14-0	0.005	0.01		83	
	non noble metal	zinc	7440-66-6	0.018	0.03		331	
	non noble metal	iron	7439-89-6	0.368	0.66		6610	
wire	non noble metal	copper	7440-50-8	14.956	26.84	27.54	268410	275434
	non noble metal	copper	7440-50-8	0.085	0.15	0.15	1518	1518
	encapsulation	organic material	carbon black	1333-86-4	0.047	0.08		834
	plastics	epoxy resin	-	2.395	4.30		42977	
	inorganic material	silicondioxide	60676-86-0	20.809	37.35	41.73	373439	417250
leadfinish	non noble metal	tin	7440-31-5	0.593	1.06	1.06	10638	10638
plating	noble metal	silver	7440-22-4	0.040	0.07	0.07	721	721
glue	plastics	epoxy resin	-	0.088	0.16		1586	
	noble metal	silver	7440-22-4	0.265	0.48	0.64	4758	6344
solder	noble metal	silver	7440-22-4	0.021	0.04		369	
	non noble metal	tin	7440-31-5	0.041	0.07		738	
	non noble metal	lead	7439-92-1	0.761	1.37	1.48	13661	14768
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		14	
	non noble metal	zinc	7440-66-6	0.003	0.01		55	
	non noble metal	iron	7439-89-6	0.062	0.11		1106	
	non noble metal	copper	7440-50-8	2.502	4.49	4.61	44901	46076
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.003	0.01		61	
	non noble metal	zinc	7440-66-6	0.014	0.02		245	
	non noble metal	iron	7439-89-6	0.273	0.49		4892	
	non noble metal	copper	7440-50-8	11.069	19.86	20.38	198642	203840
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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